

High Resolution Ultrasound Transducers and Arrays for Medical Imaging Applications

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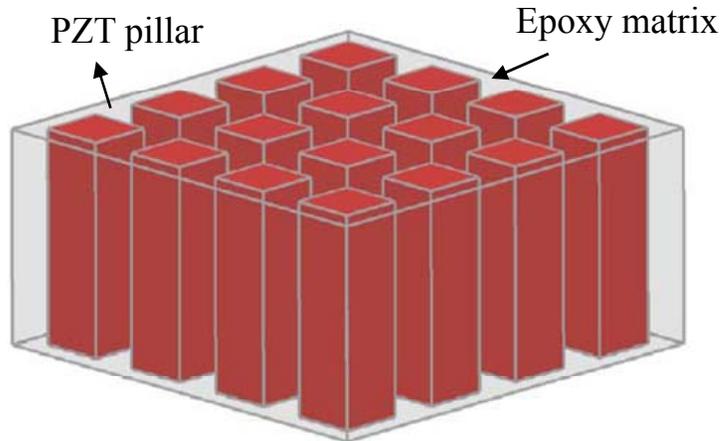
Outline

- Introduction
- Fabrication of high frequency piezocomposites and arrays
- Single element transducers
- Process improvements for HFUS arrays
- Array transducers
- Summary, commercial prospects and ongoing work

Introduction



1-3 piezocomposites

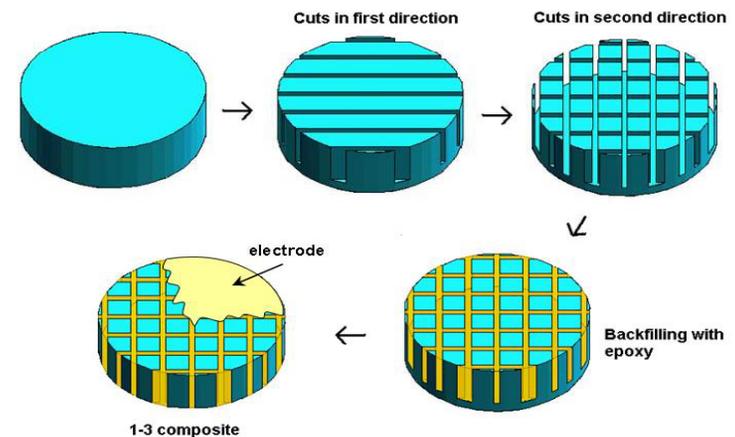


1-3 piezocomposite

- Piezocomposites made almost exclusively by the dice-and-fill technique for $f < 20\text{MHz}$
- Impossible to fabricate high frequency arrays by dice and fill because of the ultrafine feature size required.

Dimension requirements

Frequency	20 MHz	40 MHz
Pillar width	24 μm	14 μm
Kerf	20 μm	8 μm
Thickness	80 μm	40 μm



Conventional dice-and-fill technique

High Frequency Ultrasound (HFUS)

- HFUS offers high spatial resolution ($< 100 \mu\text{m}$).
- Important clinical applications such as dermatology, ophthalmology, small parts imaging, oncology diagnosis and monitoring, intravascular ultrasound and dentistry.
- The development of miniaturised transducer arrays is critical to the successful adoption of HFUS systems.
- For example, a 50 MHz linear array specification:
 - Imaging wavelength: $30 \mu\text{m}$,
 - Element pitch: $30 \mu\text{m}$
 - Piezoelectric composite substrate thickness: $40 \mu\text{m}$.
- Advances in fabrication techniques are needed.

A New Fabrication Concept

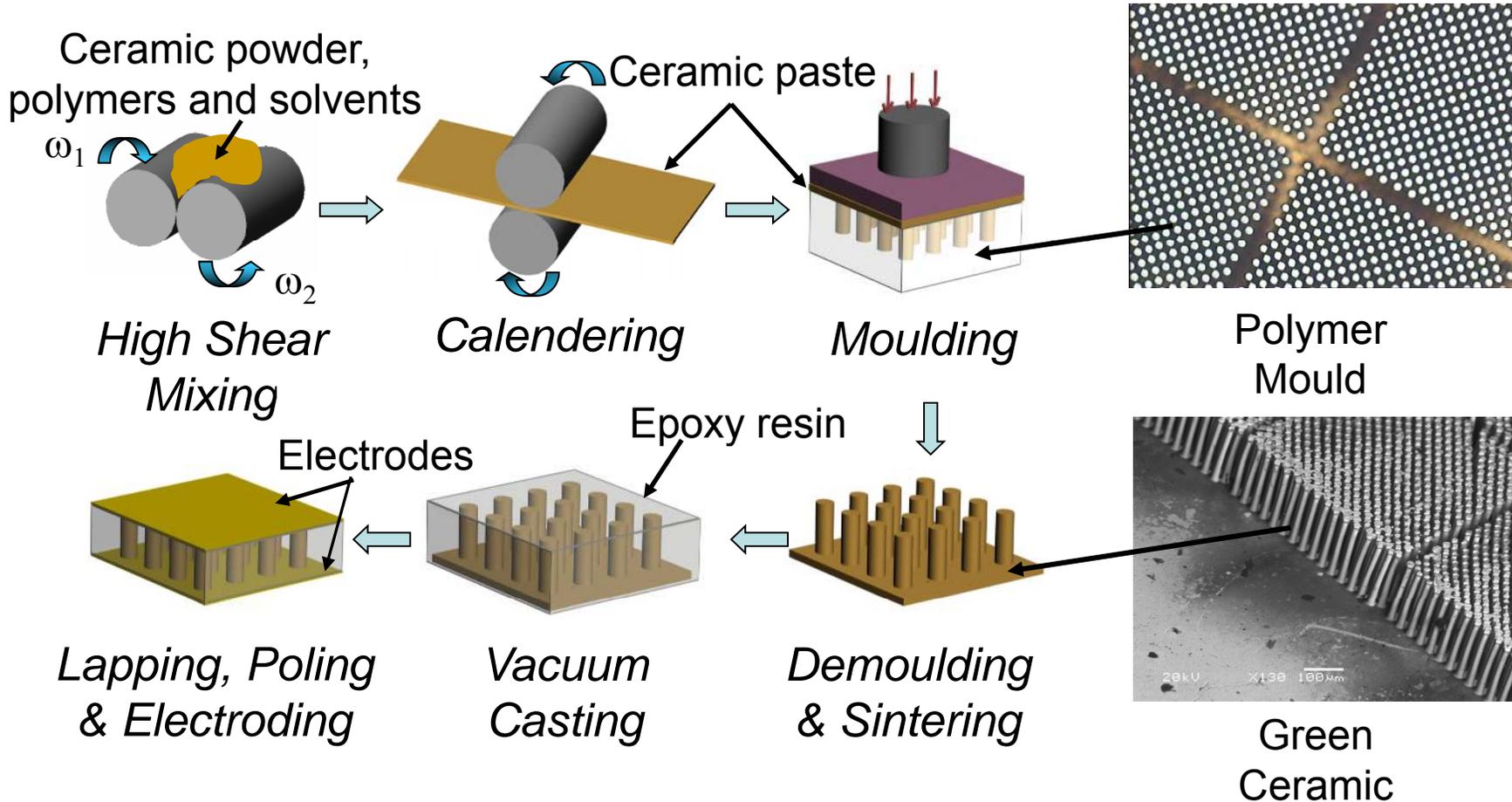
- New scalable and mask-based approach to device fabrication suitable for high frequency US arrays.
- Micromoulding for fine-scale 1-3 piezoelectric composites.
- Photolithographic definition of array elements on the composite substrates.
- High density interconnect and packaging solutions.
- Design approaches and fabrication processes that have the potential to produce arrays operating up to 100 MHz.
- Quantity scale-up via wafer-based routes leading to cost effective transducers.

Composite Fabrication

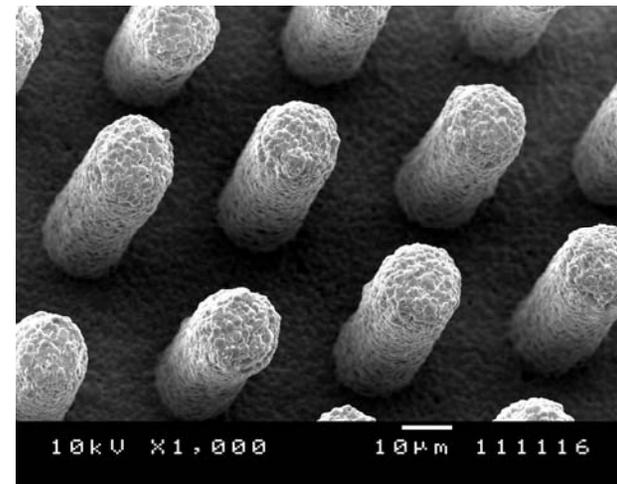
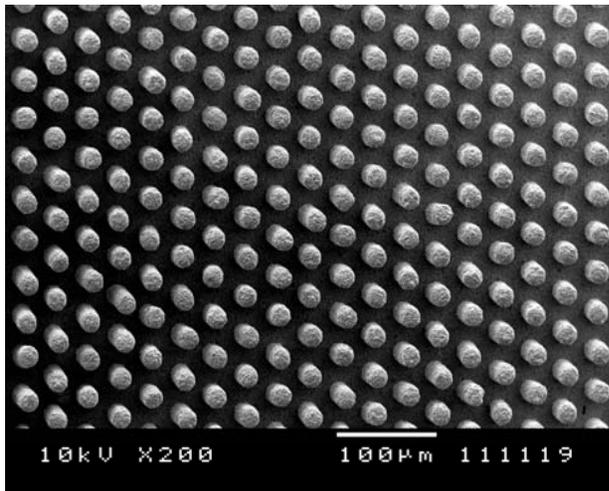
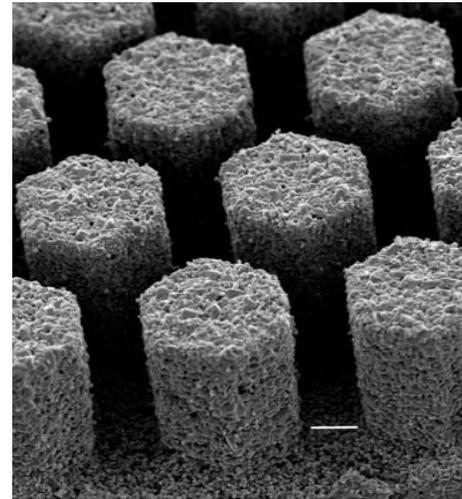
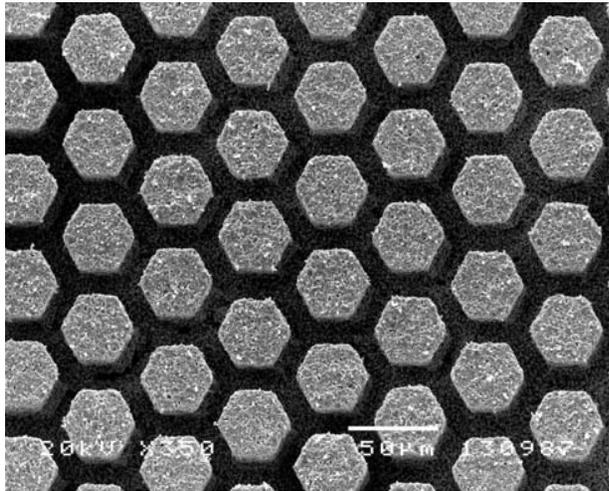


Fabrication of high frequency composites

Viscous Polymer Processing - VPP

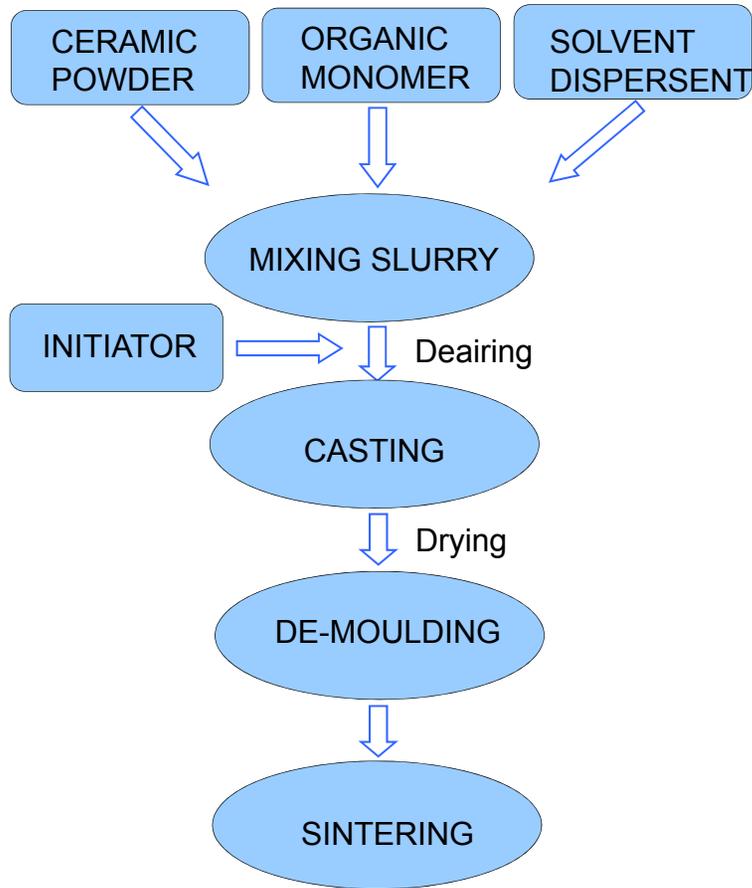


Micropillar Structures fabricated by VPP



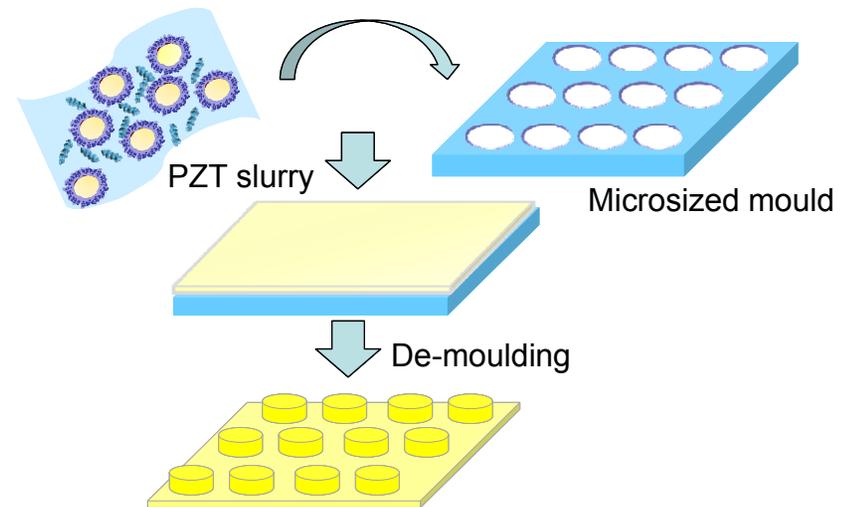
Alternative Fabrication Technique

Gel casting



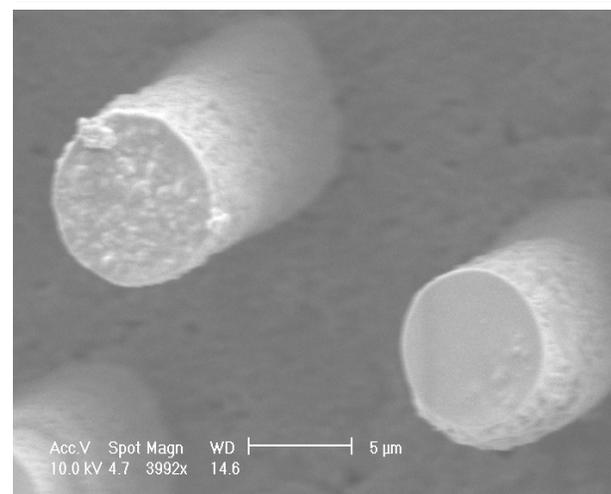
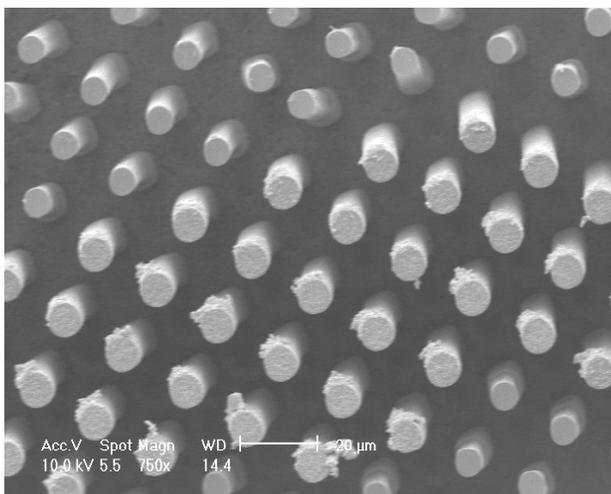
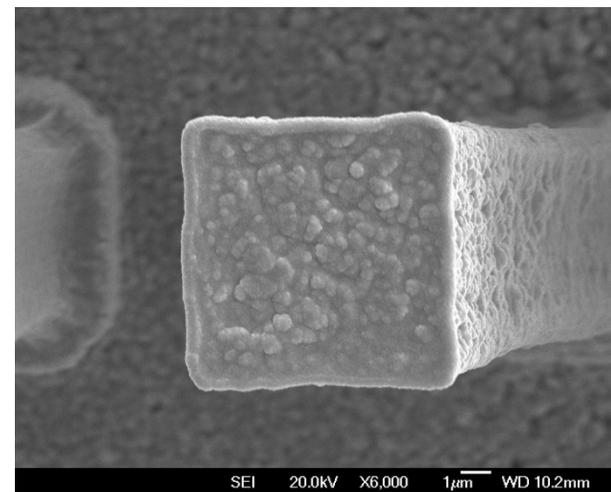
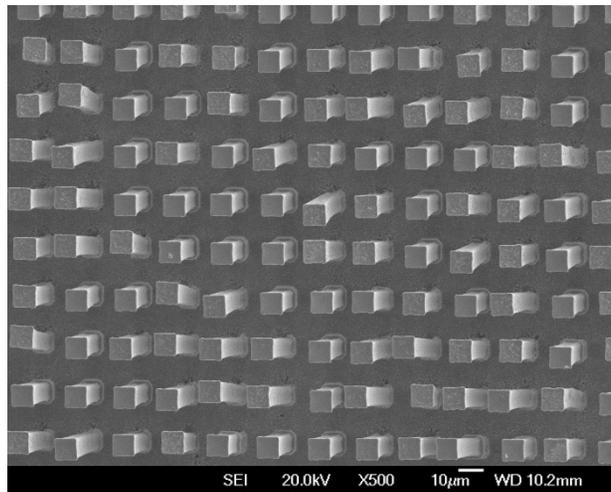
Flow chart of gel casting process.

- Capability of producing complex parts
- Homogeneous material properties
- Rapid forming cycle
- Low capital equipment cost.

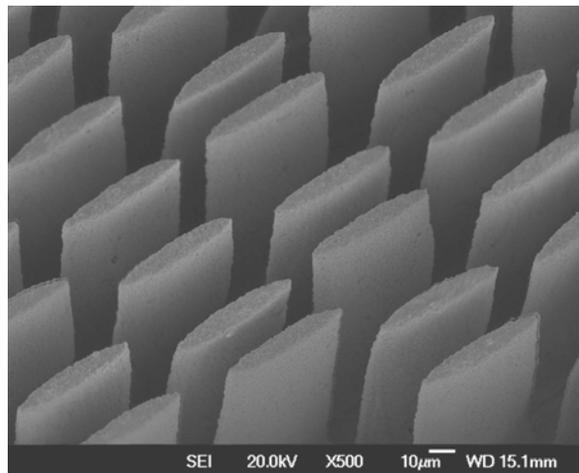
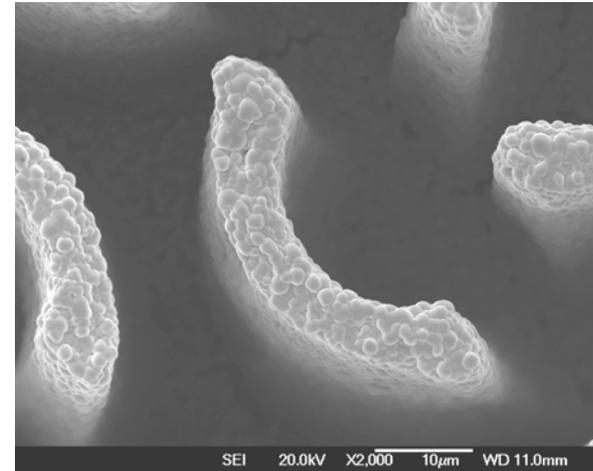
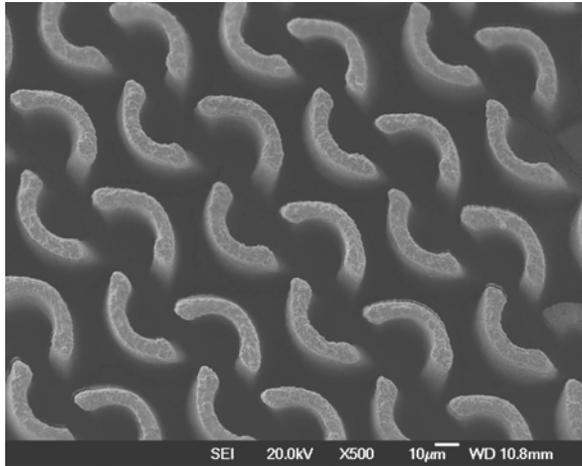


Gel casting for 1-3 piezocomposite fabrication.

Micropillar Structures fabricated by Gel casting

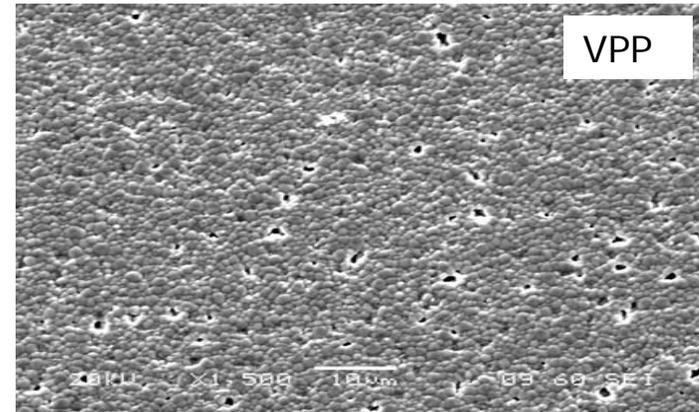
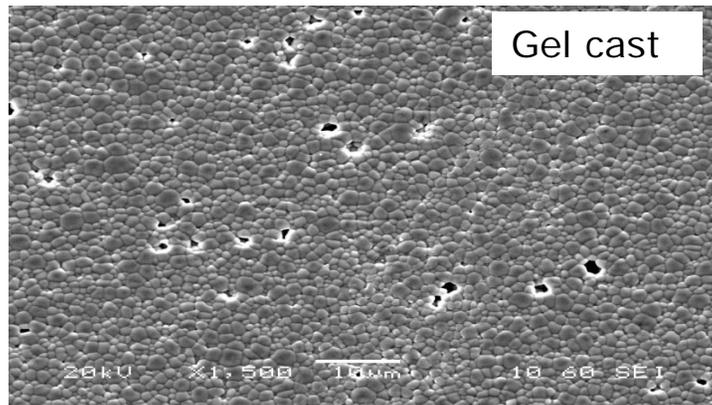


Other pillar shapes and configurations – Gel casting



Gel casting Vs VPP

Comparison of microstructure and properties of sintered bulk ceramics (TRS610C)



Sample	Density (g/cm ³)	d ₃₃ (pC/N)	k _t	Permittivity	Dielectric loss
Gel casting	7.70 ± 0.02	632 ± 9.3	0.56 ± 0.001	3200	0.019
VPP	7.65 ± 0.05	586 ± 10.5	0.52 ± 0.002	3040	0.018

Piezocomposite Material Characterisation

- Material parameters determined by fitting electrical impedance to model
- Representative results for high frequency composite:
 Resonant frequency: 30 MHz
 Ceramic volume fraction: 50 %
 $k_T = 0.51$
 $d_{33} = 130 \text{ pm/V}$
 $Z_A = 17 \text{ MRayl}$
 $\epsilon_R^S = 460$
- Parameters indicative of significant potential for biomedical imaging

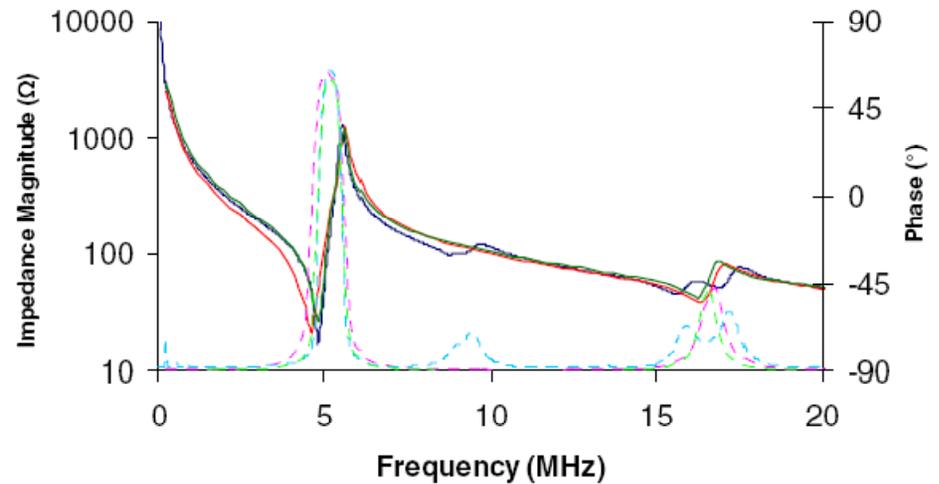


Figure 1. Measured, theoretical, and fitted electrical impedance magnitude and phase for a reference composite operating at a frequency around 5 MHz.

Impedance magnitude: Measured — Theoretical — Fitted —
 Impedance phase: Measured — Theoretical - - Fitted - -

D. MacLennan, et al., "Fundamental performance characterisation of high frequency piezocomposites made with net-shape viscous polymer processing for medical ultrasound transducers," in *Proceedings 2008 IEEE Ultrasonics Symposium*, pp. 58-61, 2008.

Single Element Transducers



30MHz single element transducers

- Transducer: piezoelectric composite, 1.6 mm diameter, 3 mm geometric focus
- Piezoelectric composite:
 - 20 μm diameter pillars
 - 29 μm pitch, hexagonal packing
 - lapped to 54 μm thick
- Packaged and backed with tungsten-loaded epoxy

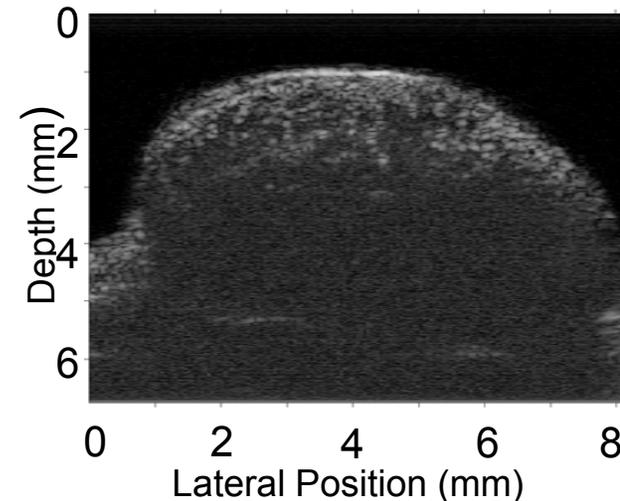


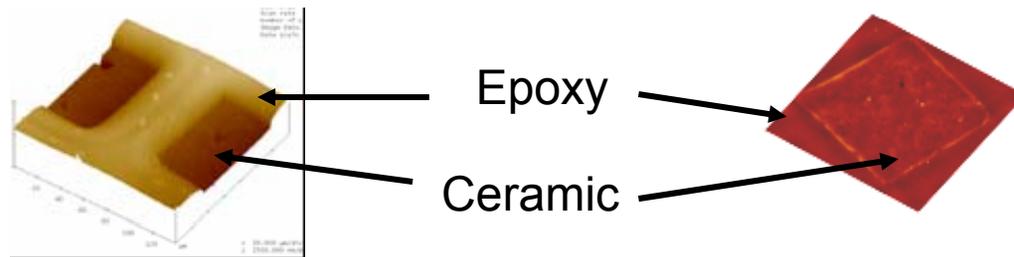
Image of mouse subcutaneous tumour xenograft acquired by mechanically scanning transducer across specimen

Process Improvements for transducer arrays



Advanced surface finishing

- Surfaces of composite must be flat, parallel and smooth in preparation for photolithography
- After standard processing, the two dissimilar materials in the composite retain surface relief
- Lapping and polishing processes have been adapted to provide flat and smooth surfaces

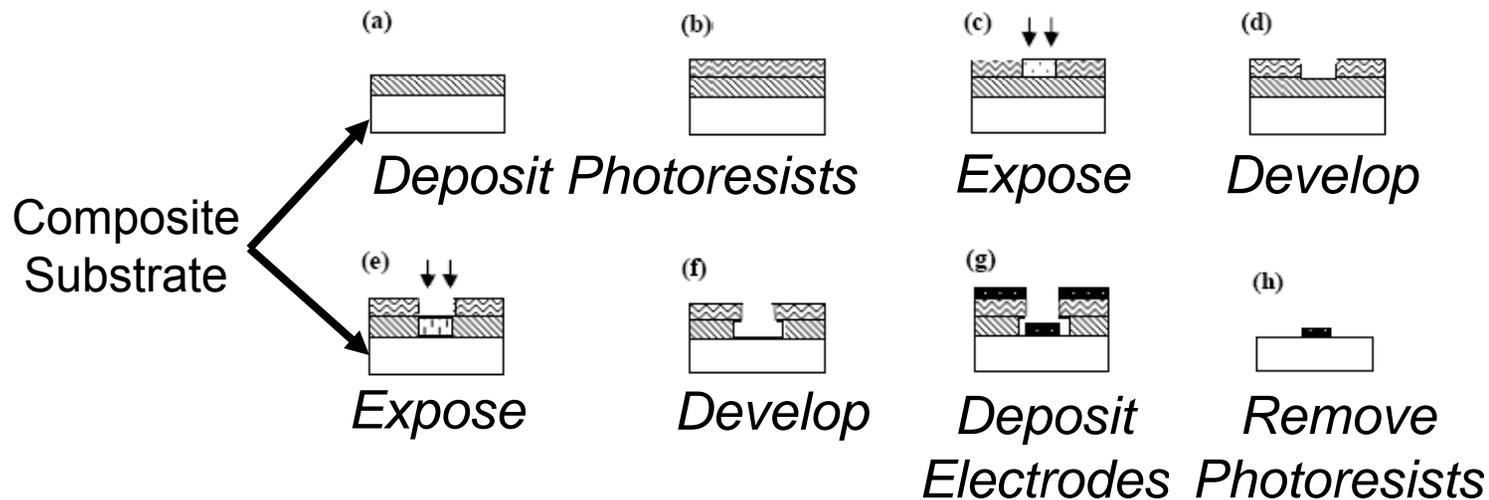


*Standard processing:
~1 μm height difference*

*Advanced processing:
60 nm height difference*

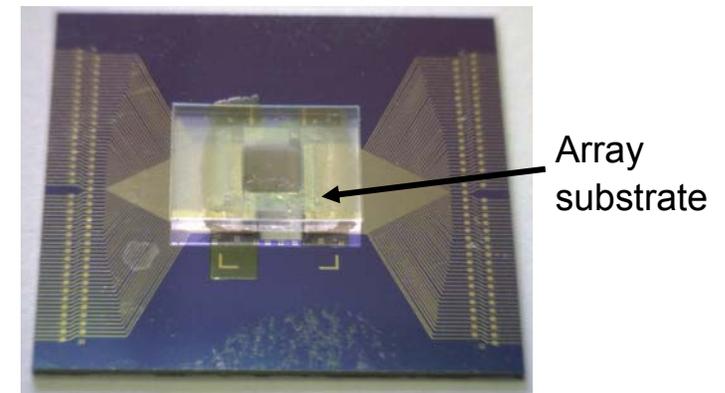
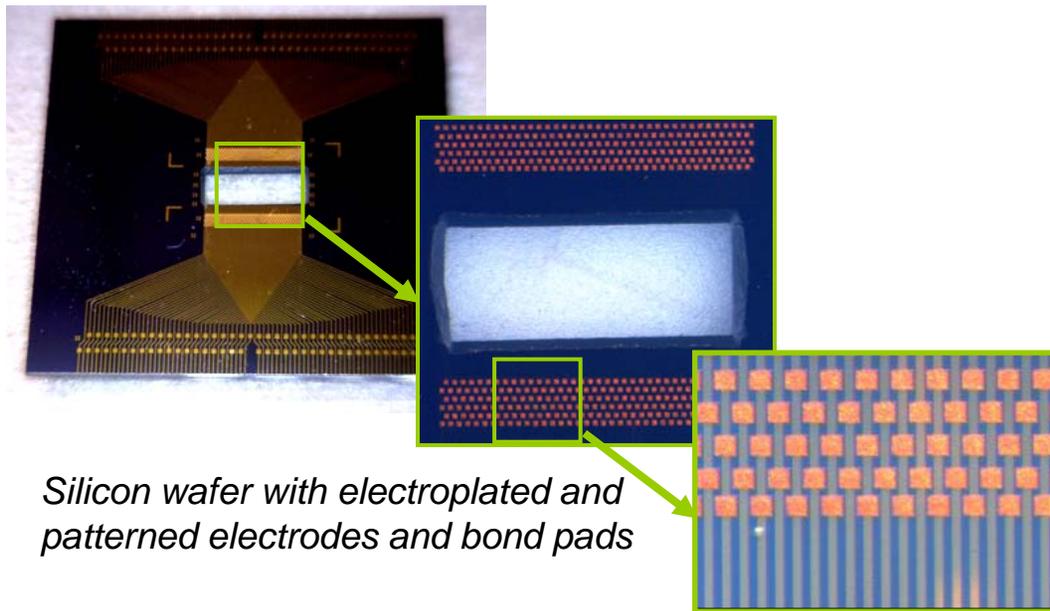
Electrode Patterning

- Lift-off photolithography process adapted for patterning electrodes on composite material
- Solvent-resistant epoxy used for composite fill
- Excellent edge definition and adhesion have been obtained



Mask-based Interconnect

- Standard wirebonding of array element electrodes to flex-circuits does not scale well for arrays above 50 MHz.
- Silicon wafer interconnect solution enables wafer scale production and can be used as a platform for further electronics integration.



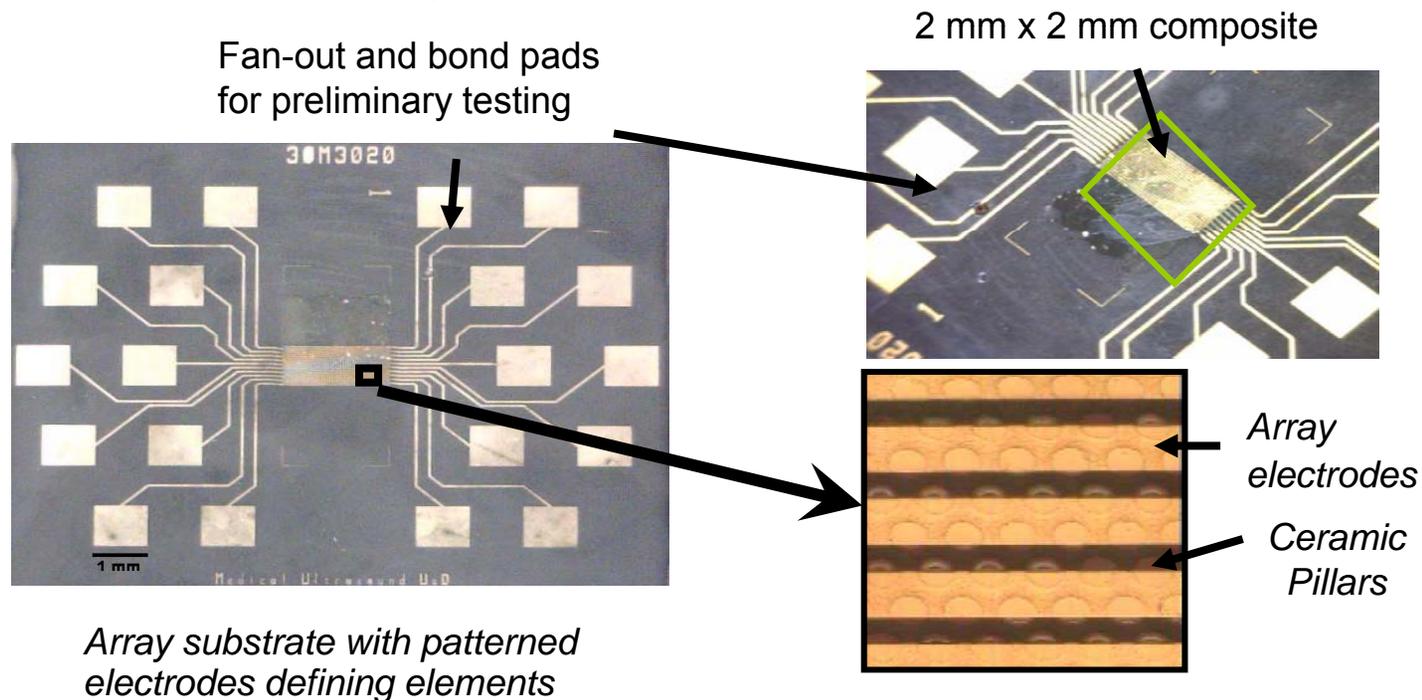
Array substrate connected to contact pads on silicon wafer with flip-chip bonding process

Transducer Arrays



30MHz linear arrays

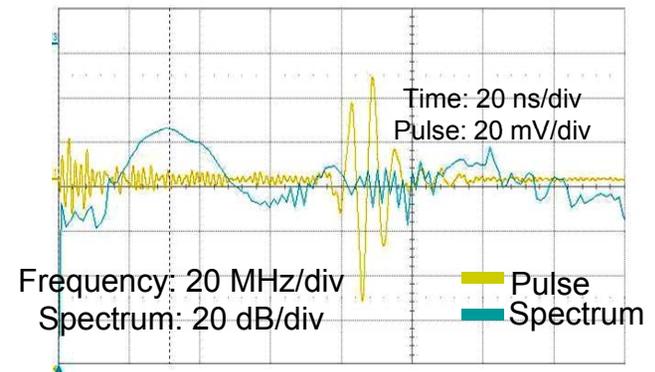
- Arrays: 20 and 32 element designs, 30 μm wide, 50 μm pitch
- Piezoelectric composite: 20 μm diameter pillars, 29 μm pitch, hexagonal packing, lapped to 55 μm thick
- Wired, packaged and backed with unloaded epoxy for preliminary testing



30MHz linear arrays

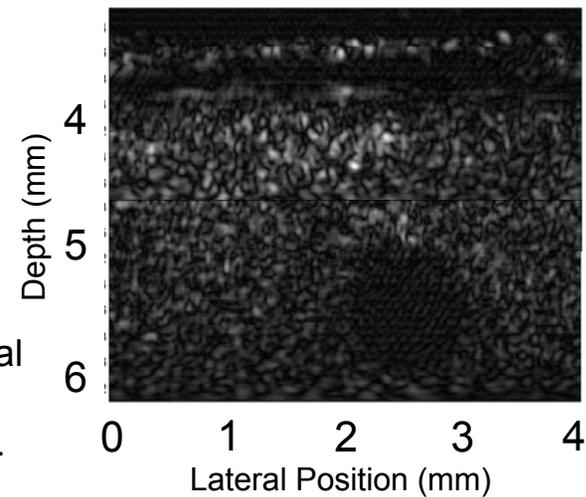


Packaged Prototype Array



Pulse-echo response of single element from quartz flat
Centre Frequency: 31 MHz, Bandwidth: 50 %

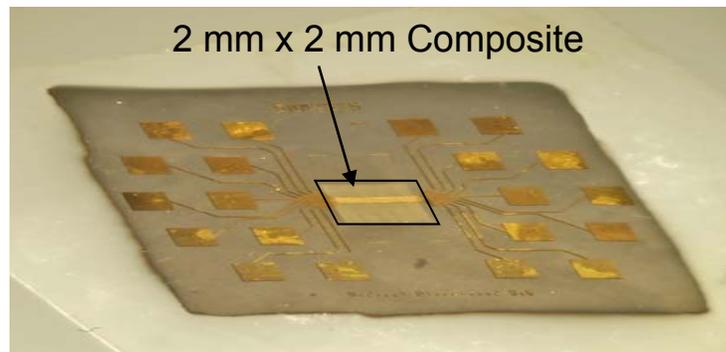
Synthetic aperture Image of 1 mm cylindrical
cyst phantom in scattering background.
Synthesised aperture: 4 mm, pitch: 10 μm .



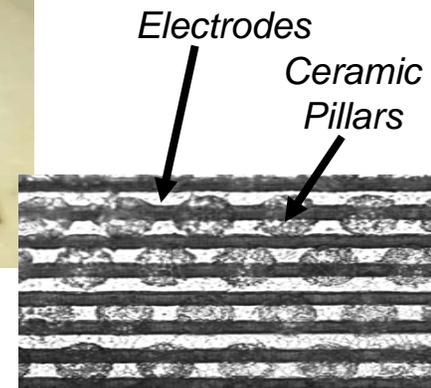
100MHz linear array pattern

Proof of Concept

- Array: 20 elements, 7.5 μm wide, 15 μm pitch
- Piezoelectric composite: 40 μm thick (for 50MHz operation)
- Wired, packaged and backed with unloaded epoxy for preliminary testing



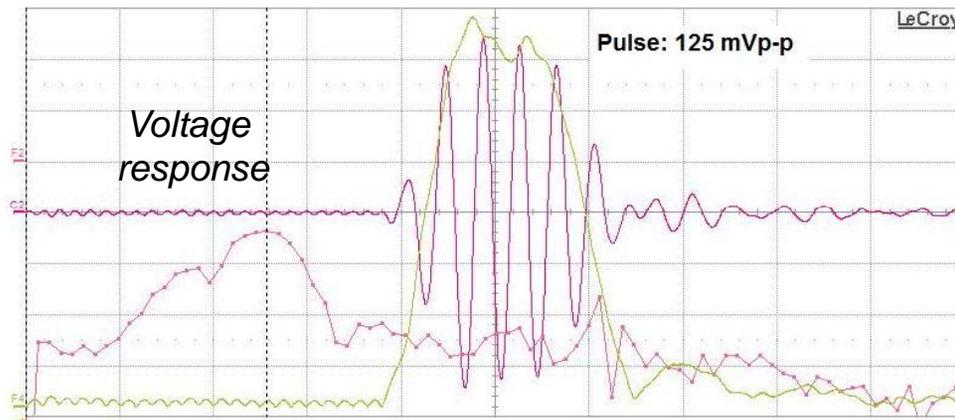
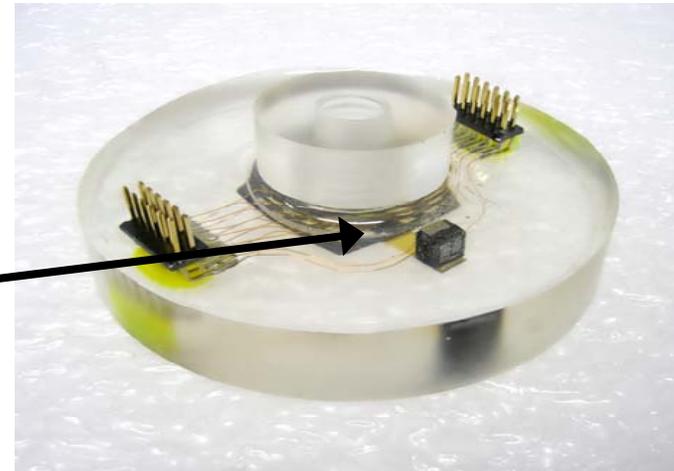
Composite substrate with patterned array electrodes



100MHz linear array pattern

Array wired to connectors and packaged for testing

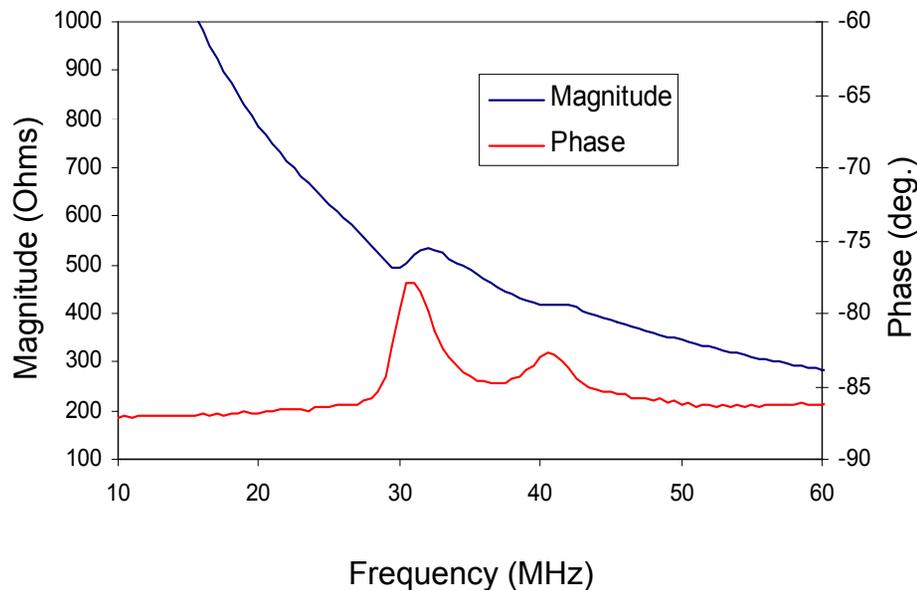
Array substrate



*Pulse-echo response of single element from quartz flat.
Centre Frequency: 51 MHz,
Bandwidth: 25 %*

Electrical Impedance

Electrical Impedance of representative element in 30 MHz array



30 MHz array

- Thickness mode frequency at 30 MHz
 - Lateral mode at 40 MHz due to unoptimised composite
- Elements across array have uniform performance
 - Response consistent with expected performance

100 MHz array

- Elements show piezoelectric response
 - 45 MHz thickness mode
 - Response is highly damped because array pattern very small relative to composite

Potential Applications

Applications for 30 – 100 MHz arrays can be found in the many clinical disciplines which require:

- High spatial resolution
- Real-time imaging

- Example: Dermatology

- High frequency arrays can be used to enhance 3D and reflex transmission imaging (RTI) by varying the focus through the depth of the tissue in real time
 - RTI measures the attenuation of tissue at the focus of a strongly focused transducer
- RTI with high frequency arrays has potential for improving the accuracy and efficiency of diagnosis of melanoma

- Example: Ultrasonic and optoacoustic scanning of vasculature

- The synthetic focusing possible with arrays is required for optoacoustic imaging of oxygenated and deoxygenated blood
- With high frequency arrays, accurate imaging of microvasculature becomes possible, leading to improved diagnosis and monitoring of many diseases

Summary

- Micromoulding and microfabrication processes have been developed for fabricating fine-scale, HFUS transducer arrays.
- Micromoulded piezoelectric composites with material properties suitable for high frequency imaging have been made.
- Surface finishing and photolithography techniques have been developed and adapted to pattern fine-scale arrays directly on composite surfaces.
- Prototype arrays have been fabricated and perform as expected.

Commercial Prospects

- HFUS is already here!
 - VisualSonics, SonoSite
- Interest in HF from most major Ultrasound players
- Specific applications for HF single element devices
- Cost effective fabrication for HF Arrays (>15 MHz) required
- Wide range of potential applications

Future Work

- Optimise piezoelectric composite and array designs for improved performance at 50 MHz and above.
- Further develop technologies for interconnect between arrays and silicon wafers.
- Integration of HFUS arrays with electronics to minimise cable issues
 - preliminary demonstration of combining a HFUS transducer with an ASIC in collaboration with Penn State
(Bernassau et al, IEEE Ultrasonics Symp, Rome 2009).
- Application specific programmes.